

CHIPQUIK® SMDAU80SN20-3inch-0.762mm

Datasheet revision 1.3

www.chipquik.com

Solder Wire (Au80/Sn20) Gold/Tin Eutectic 0.030"/0.762mm diameter - 3 inches

Product Highlights

Gold/Tin 80/20 Eutectic Solder Alloy

Lead-Free

RoHS 3 compliant

REACH compliant

Gold/Tin (80 percent Gold, 20 percent Tin) Solid Core Solder Wire. Eutectic, melts at 280°C (536°F). Au80/Sn20 alloy offers good wetting, high strength, and low creep. It has excellent corrosion resistance and a high thermal conductivity. Au80/Sn20 can be brazed without flux and is suitable for use in vacuum environments. This alloy is used in many applications, including die attachment of semiconductor packages and metal lids.



Common Applications

High Reliability

Die Attachment

Lid Sealing

Brazing

Specifications

Alloy:	Au80/Sn20
Diameter:	0.030" (0.762mm)
Length:	3" (76.2mm)
Net Weight:	0.5 grams
Melting Point:	280°C (526°F)
Flux Core:	Solid core wire, no flux
Density:	14.51 g/cm ³
Tensile Strength:	40,000 psi
Shear Strength:	40,000 psi
Young's Modulus:	8.57 x10 ⁶ psi
CTE (Coefficient of Thermal Expansion):	16 ppm/C (at 20C)
Thermal Conductivity:	57 W/mK
Shelf Life:	>60 months

Recommended Accessory Flux

Recommended to use with Chip Quik® SMD291NL flux.

Storage and Handling

Store in a non-corrosive, dry environment.

Mouser Electronics

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